

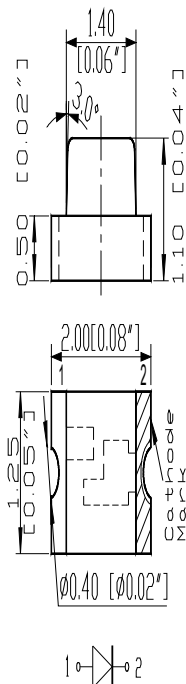
# SURFACE MOUNT LED LAMPS

## 表面黏著型發光二極體指示燈

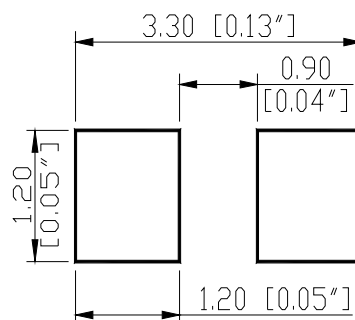
### S170 Series SMD Chip LED Lamps

Part Number: S170ANB4-C

### Package outlines



### RECOMMEND PAD LAYOUT



ITEM	MATERIALS
Resin (mold)	Epoxy
Bonding wire	↓ 25 μm Au
Lens color	Water transparent
Printed circuit board	BT (White)
Dice	GaN
Emitted color	Blue



#### NOTES:

1. All dimensions are in millimeters (inches);
2. Tolerances are  $\pm 0.1\text{mm}$  (0.004inch) unless otherwise noted.

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**Part Number: S170ANB4-C****Absolute maximum ratings (T<sub>A</sub>=25°C)**

Parameter	Symbol	Value	Unit
Forward current	I <sub>f</sub>	30	mA
Reverse voltage	V <sub>r</sub>	5	V
Power dissipation	P <sub>d</sub>	118	mW
Operating temperature range	T <sub>op</sub>	-20 ~+80	°C
Storage temperature range	T <sub>stg</sub>	-20 ~+80	°C
Peak pulsing current (1/8 duty f=1kHz)	I <sub>fp</sub>	125	mA

**Electro-optical characteristics (T<sub>A</sub>=25°C)**

Parameter	Test Condition	Symbol	Value	Unit
Wavelength at peak emission (Typ.)	I <sub>f</sub> =20mA	λ <sub>peak</sub>	460	nm
Spectral half bandwidth (Typ.)	I <sub>f</sub> =20mA	Δλ	37	nm
Dominant wavelength (Typ.)	I <sub>f</sub> =20mA	λ <sub>dom</sub>	470	nm
Viewing angle at 50% I <sub>v</sub> (Typ.)	I <sub>f</sub> =10mA	2θ <sub>1/2</sub>	140	Deg
Reverse current (Max.)	V <sub>r</sub> =5V	I <sub>r</sub>	10	μA
(Typ.)	I <sub>f</sub> =20mA	V <sub>f</sub>	3.60	V
Forward voltage (Max.)			4.20	
CIE Coordinates X (Typ.)	I <sub>f</sub> =20mA	--	0.1441	--
Y (Typ.)			0.0768	
Luminous intensity (Min.)	I <sub>f</sub> =20mA	I <sub>v</sub>	55	mcd

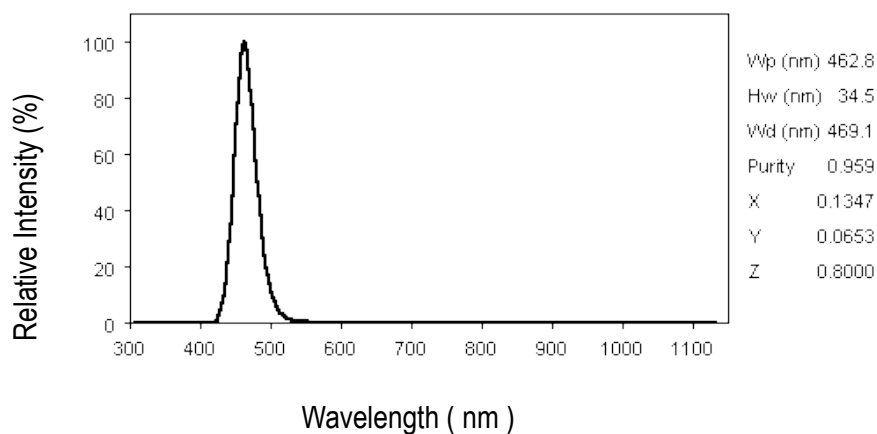
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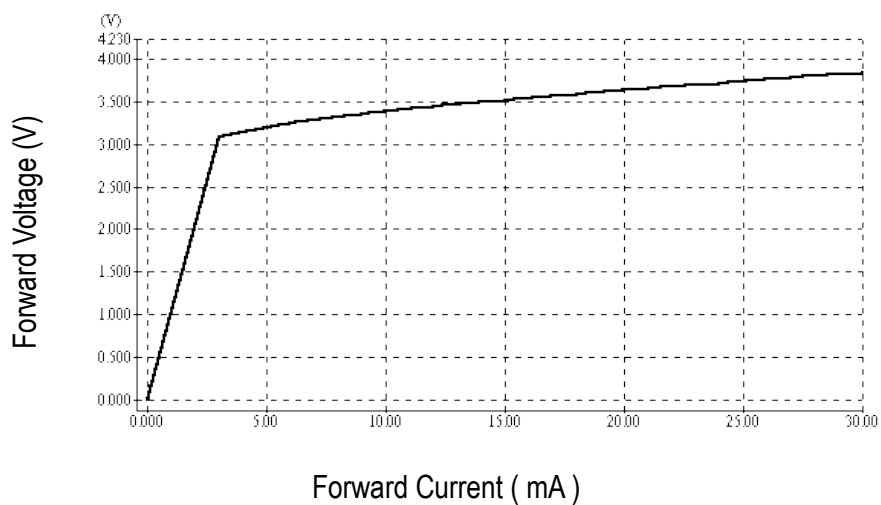
Part Number: S170ANB4-C

### OPTICAL CHARACTERISTIC CURVES

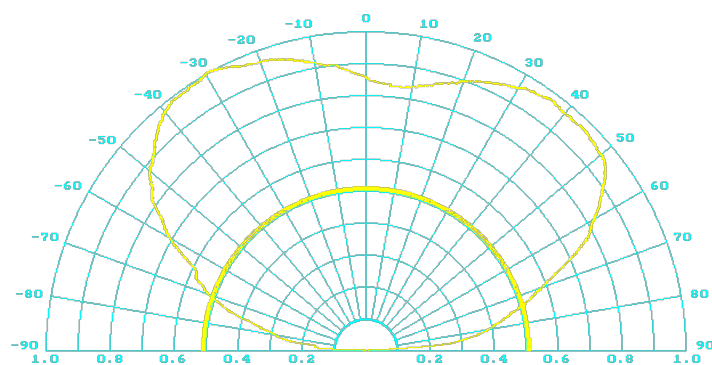
Relative Intensity vs. Wavelength



Forward Current vs. Forward Voltage



Directive Characteristics

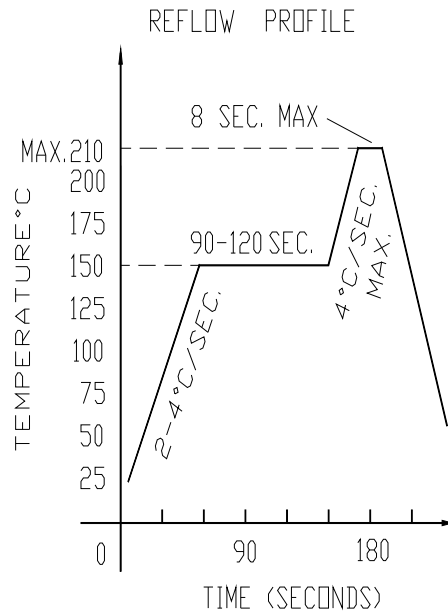


# **SURFACE MOUNT LED LAMPS**

**表面黏著型發光二極體指示燈**

**Reflow Profile**

## ■ Reflow Temp/Time

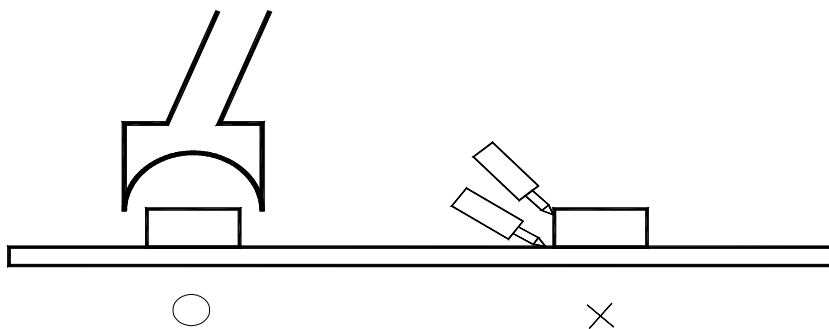


## ■ Soldering iron

Basic spec is  $\leq 5\text{sec}$  when  $260^\circ\text{C}$ . If temperature is higher, time should be shorter ( $+10^\circ\text{C} \rightarrow -1\text{sec}$ ). Power dissipation of iron should be smaller than 15W, and temperatures should be controllable. Surface temperature of the device should be under  $230^\circ\text{C}$ .

## ■ Rework

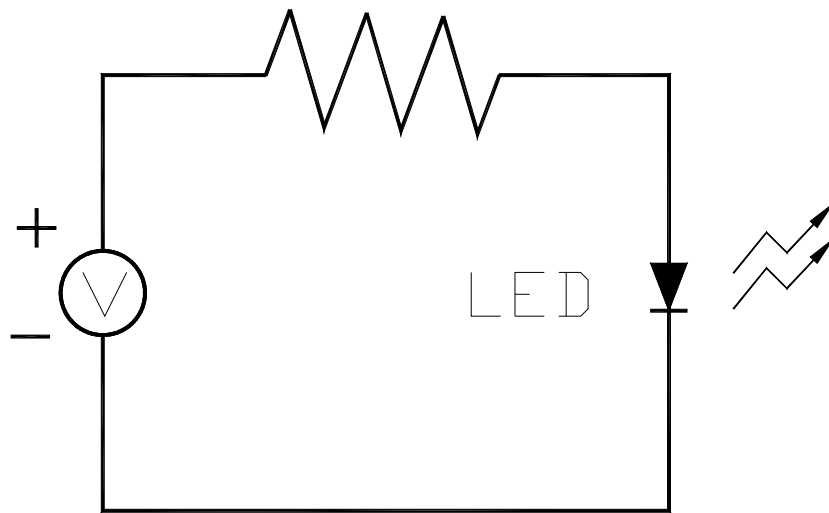
1. Customer must finish rework within 5 sec under  $260^\circ\text{C}$ .
2. The head of iron can not touch copper foil
3. Twin-head type is preferred.



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## TEST CIRCUIT



#### ■Precautions For use

Over-current-proof

Customer must apply resistors for protection; otherwise slight voltage shift will cause big current change (Burn out will happen).

## SURFACE MOUNT LED LAMPS

表面貼裝型發光二極管LED

## Test items and results of reliability

Type	Test Item	REF. Standard	Test Conditions	Note	Number of Damaged
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Sequential Environmental

Sequential Environmental	Temperature Cycle	JIS C 7021 (1977)A-4	-20°C 30min ↑↓5min 80°C 30min	100 cycle	0/100
	Thermal Shock	MIL-STD- 107D	-20°C 15min ↑↓ 80°C 15min	100 cycle	0/100

	High Humidity Heat Cycle	JIS C 7021 (1977)A-5	30°C↔ 65°C 90%RH 24hrs/1cycle	10 cycle	0/100
	High Temperature Storage	JIS C 7021 (1977)B-10	T <sub>a</sub> =80°C	1000 hrs	0/100
	Humidity Heat Storage	JIS C 7021 (1977)B-11	T <sub>a</sub> =60°C RH=90%	1000 hrs	0/100
<b>Se<sub>Q</sub>peration</b>	Low Temperature Storage	JIS C 7021 (1977)B-12	T <sub>a</sub> =-30°C	1000 hrs	0/100
	Life Test	JIS C 7035 (1985)	T <sub>a</sub> =25°C I <sub>F</sub> =20mA	1000 hrs	0/100
	High Humidity Heat Life Test	*	60°C RH=90% I <sub>F</sub> =20mA	500 hrs	0/100
	Low Temperature Life Test	*	T <sub>a</sub> =-20°C I <sub>F</sub> =20mA	1000 hrs	0/100

\* Refer to reliability test standard specification for in this line.